DERWENT-ACC-NO: 1999-220856
DERWENT-WEEK: 199919

TITLE: Flip-chip mounting structure for electronic component - has solder
bumps which are formed on conductive resin film via metal plating film

PATENT-ASSIGNEE: MATSUSHITA DENKI SANGYO KK[MATU]

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 11054672 A	February 26, 1999	N/A	005	H01L 023/32

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
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INT-CL (IPC): H01L023/12; H01L023/32

ABSTRACTED-PUB-NO: JP 11054672A
BASIC-ABSTRACT: NOVELTY - Electrodes (2) are formed on a substrate (1) via a
conductive resin film (3). Solder bumps (5) are formed on the conductive film
via a metal plating film (4). A flip-chip (7) is mounted via a solder (8) on
the electrodes.

USE - For electronic component.

ADVANTAGE - Since, the conductive resin layer has high elasticity it absorbs
the thermal variation exerted. Prevents solder bump's crack and dependability
of electronic component after mounting of flip-chip is increased. DESCRIPTION
OF DRAWING(S) - The figure illustrates the sectional view of

the flip-chip
mounting structure. (1) Substrate; (2) Electrode; (3)
Conductive resin film;
(4) Metal plating film; (5) Solder bump; (7) Flip-chip; (8)
Solder.

CHOSEN-DRAWING: Dwg.1/5

TITLE-TERMS:
FLIP CHIP MOUNT STRUCTURE ELECTRONIC COMPONENT SOLDER BUMP
FORMING CONDUCTING
RESIN FILM METAL PLATE FILM

DERWENT-CLASS: U11

EPI-CODES: U11-E01C;

SECONDARY-ACC-NO:
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